



THE SUPERSCALAR HARDWARE ARCHITECTURE OF THE MC68060

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Application of Superscalar Design Techniques to CISC Instruction Sets

- **Implementation is complicated by:**
 - Variable-length instructions
 - Multiple instruction formats
 - Traditional "condition code" indicators
- **For well-established architectures,**
 - Simple recompilation may be an unacceptable solution
- **Superscalar hardware architecture must provide an acceptable performance improvement on existing object code**

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The Superscalar Microarchitecture of the MC68060

- Independent and decoupled four-stage pipelines
 - Instruction Fetch Pipeline (IFP)
 - IAG instruction address generation
 - IC instruction fetch cycle
 - IED instruction early decode
 - IB instruction buffer
 - Operand Execution Pipelines (OEPs)
 - DS decode instructions + select components of operand address
 - AG operand address generation
 - OC operand fetch cycle
 - EX instruction execution
 - OEPs consist of two pipelines operating in lockstep
 - Primary OEP (pOEP) & secondary OEP (sOEP)

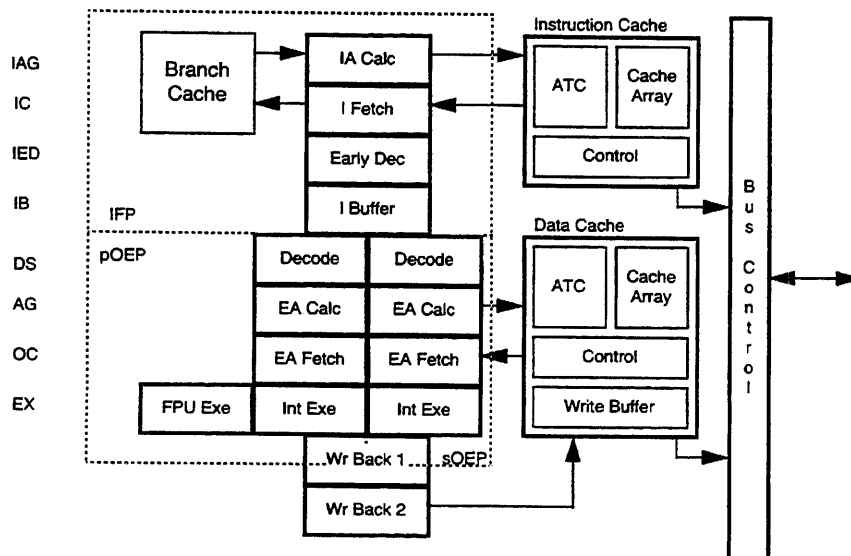
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MC68060 Block Diagram



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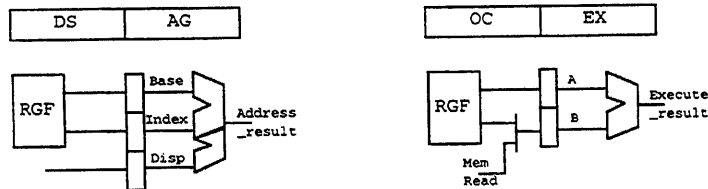


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Conceptual Model of the Operand Execution Pipeline

- Each execution pipeline consists of two "compute engines"
 - Operand address generation
 - Instruction execution
- Each compute engine follows the RISC model
 - Register file with dual read ports + ALU datapath



Resources = f(Base, Index, Address_result, A, B, Execute_result)

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Conceptual Model of the OEPs (cont.)

- This model is the foundation of the 68060 microarchitecture
- Six key elements which support the model:
 - "Early decode" function within the IFP
 - Loading of fetched instruction stream into the FIFO lbuffer
 - Superscalar dispatch algorithm located in the DS stage of the OEP
 - Result forwarding within the n-tuple of issued instructions
 - "Dynamic execution relocation" between the two compute engines
 - Optimized branch execution including 256-entry Branch Cache

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"Early Decode" within the IFP

- **Table lookup scheme**
 - 16-bit opcode produces a decode longword
 - Identifies all the resources required by the instruction {memory, immediate, register} operands
 - Allows efficient evaluation of the dispatch algorithm
- **Additional information to control the DS stage of the OEP**
 - Instruction length
 - Operand type and address generation
- **Fixed-length decode**
 - Translates various instruction formats
 - Single definition which is used by the OEPs

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Loading Fetched Instruction Stream

- **Given a variable-length ISA and the ability to issue multiple instructions, how is the next set of instructions loaded into the execution pipeline?**

The 68060 solution is the use of a FIFO instruction buffer

- **Packaged as machine instructions**
 - Use instruction length from early decode
 - Each buffer entry is 1 instruction
- **FIFO buffer implemented with three read ports**
 - If current pOEP instruction is location i of FIFO, then FIFO reads at locations $(i+1)$, $(i+2)$, $(i+3)$
 - Allows the $\{(i+1),(i+2)\}$ or $\{(i+2),(i+3)\}$ pair to be sent to OEPs

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Superscalar Dispatch Algorithm

- **Evaluates a series of tests (DS stage)**
 - Using early decode information, potential conflicts analyzed
- **Data hazards between pOEP and sOEP**
 - Inputs to sOEP must not be outputs from pOEP
 - If hazard is detected, then the sOEP instruction cannot be issued
- **If all tests successful, both instructions issued to the AG stage**
- **If any test fails, only the pOEP instruction is issued**

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Result Forwarding within the Dispatched Group

- **In 2-operand ISAs**
 - Simple assignment instructions used extensively
 - **Example:**

```
mov.l (d,A0),D0 # move memory-to-register
add.l D1,D0    # register-to-register operation
```

Data hazard involving D0
- **Avoid the detection of the data hazard**
 - Rename the operand {destination = source} for simple assignments
- **2 heavily-used constructs benefit:**

```
mov.l <ea>,Rx
<op> Rx      # Rx can be either source and/or destination

<op>.l <ea>,Rx
mov.l Rx,<mem>
```

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Dynamic Execution Relocation

- For most opcodes,
 - DS/AG engine used for address generation
 - OC/EX engine used for instruction execution
- Certain opcodes “executed” by DS/AG engine
 - Register renaming techniques
 - Results available with no pipeline stalls
- ‘060 adds third category
 - Opcodes which can be executed by either engine
 - Relocation from OC/EX to DS/AG
 - Allows more effective use of register renaming hardware
 - Minimize pipeline stalls
 - If no pending register writes to source operands at issue time,
 - Relocate the execution from OC/EX to DS/AG

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Optimized Branch Execution

- 256-entry Branch Cache Unit within the IFP
 - Hardware table associating branch PC and target address
 - Organized as 4-way set-associative (4 x 64)
 - 4-state prediction model
- Instruction folding
 - Executes taken branches predicted correctly in 0 cycles
- Pipeline optimized for correct prediction
 - If mis-prediction, then
 - IFP & OEPs are aborted
 - New instruction stream established
- Execution Strategy for Non-Predicted Branches
 - Assumed branch resolution = f(branch direction)
 - If forward branch, then assumed to be not-taken
 - If backward, then the branch is assumed to be taken

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MC68060 Summary

- **Measured Performance**
 - 1.2 CPI measured on range of desktop and embedded applications
 - 45-55% of instructions issued as pairs/triplets (existing 680X0 code)
 - 50-65% of instructions issued as pairs/triplets (targeted 68060 code)
 - 68060-50 = 2.5x - 3.5x 68040-25; 68060-66 = 2.1x - 2.9x 68040-40
- **Features**
 - 2.5 million transistors, 0.5u TLM 3.3v process
 - Interfaces to 5v logic
 - Supports full, 1/2, and 1/4 speed buses
 - Worst case power dissipation of 3.9w at 50MHz
 - Sampling now; production ramp 4Q94
- **Maintains hardware & software compatibility with the largest installed base of 32-bit embedded control microprocessors in the world**

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